
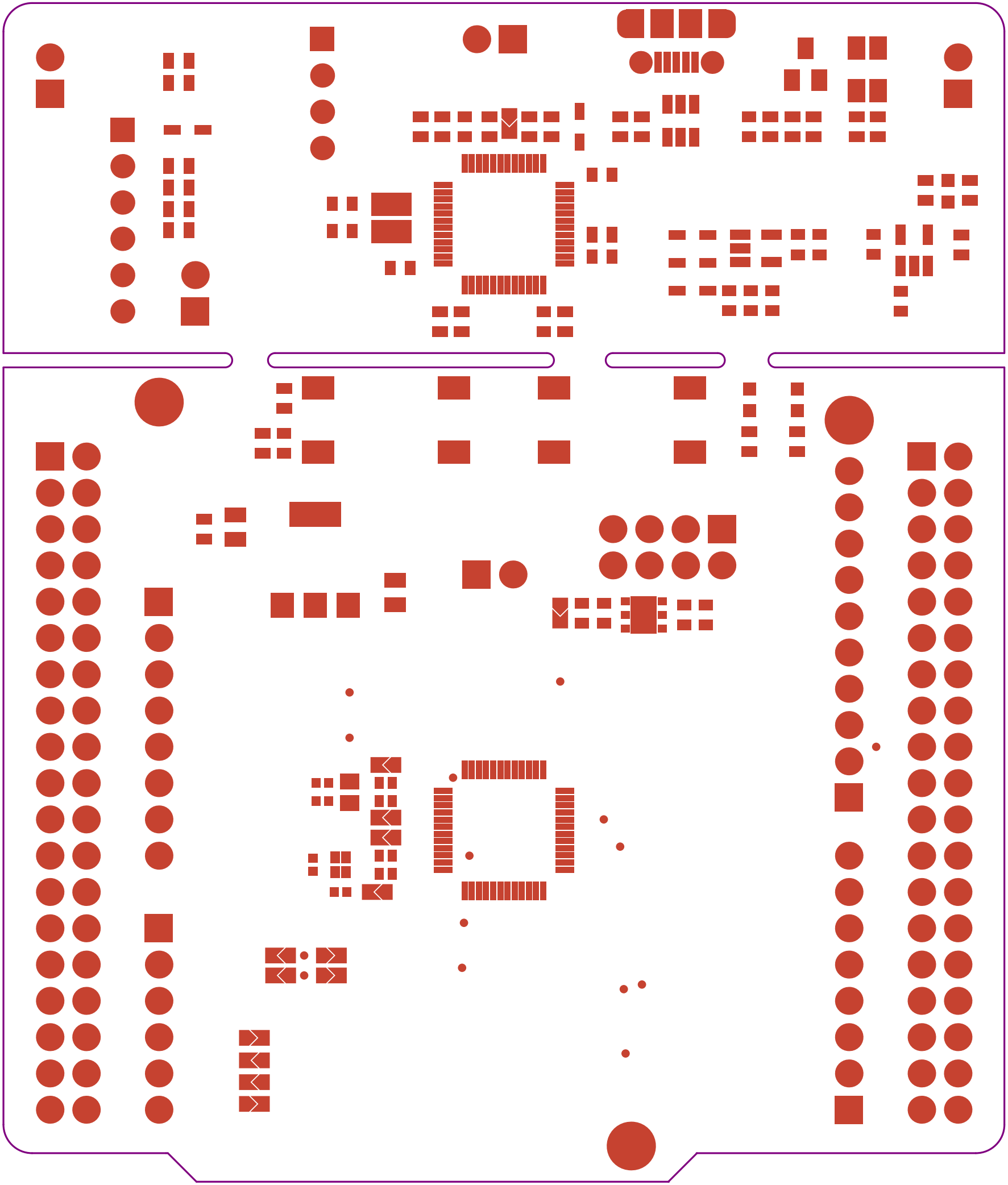

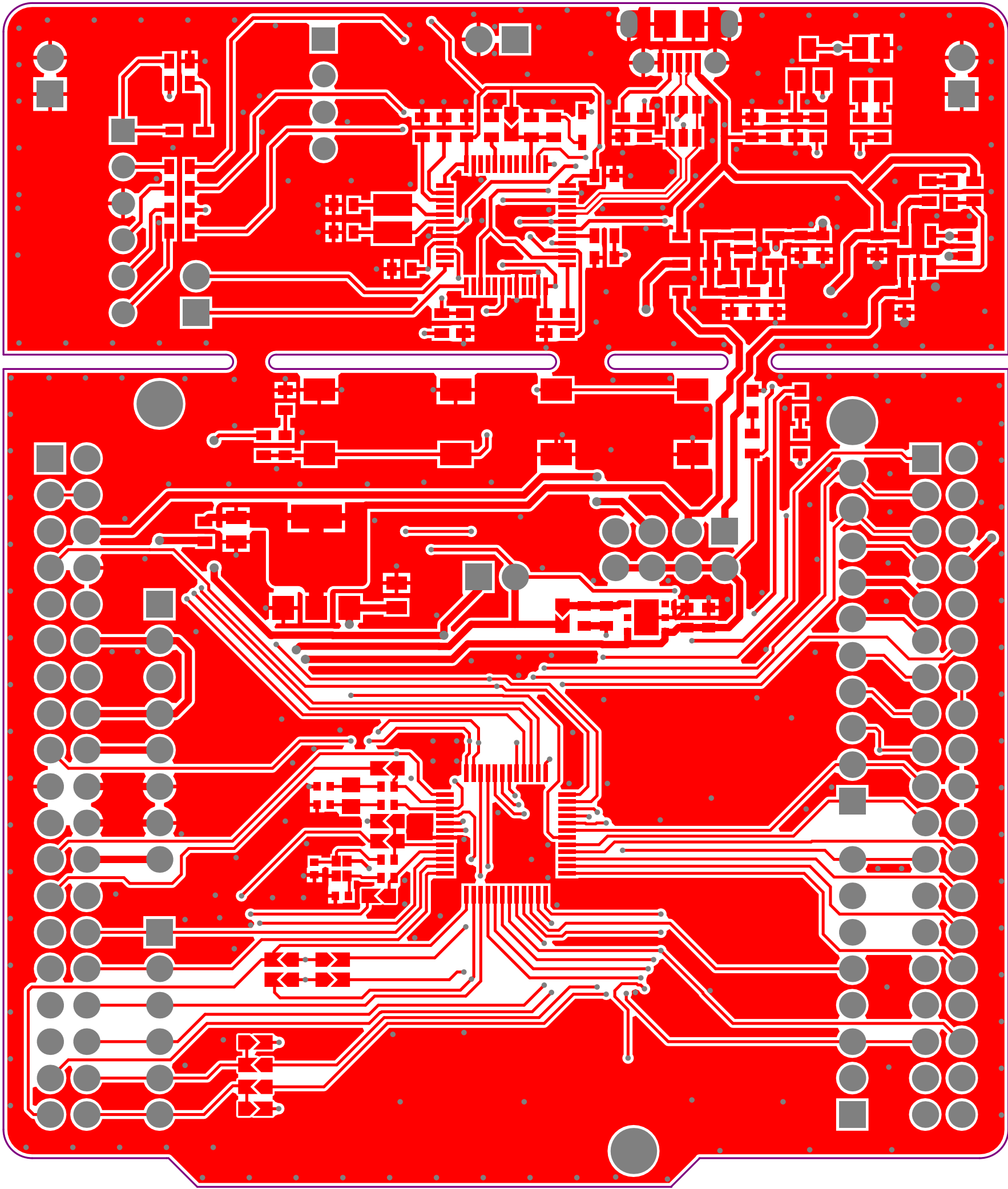



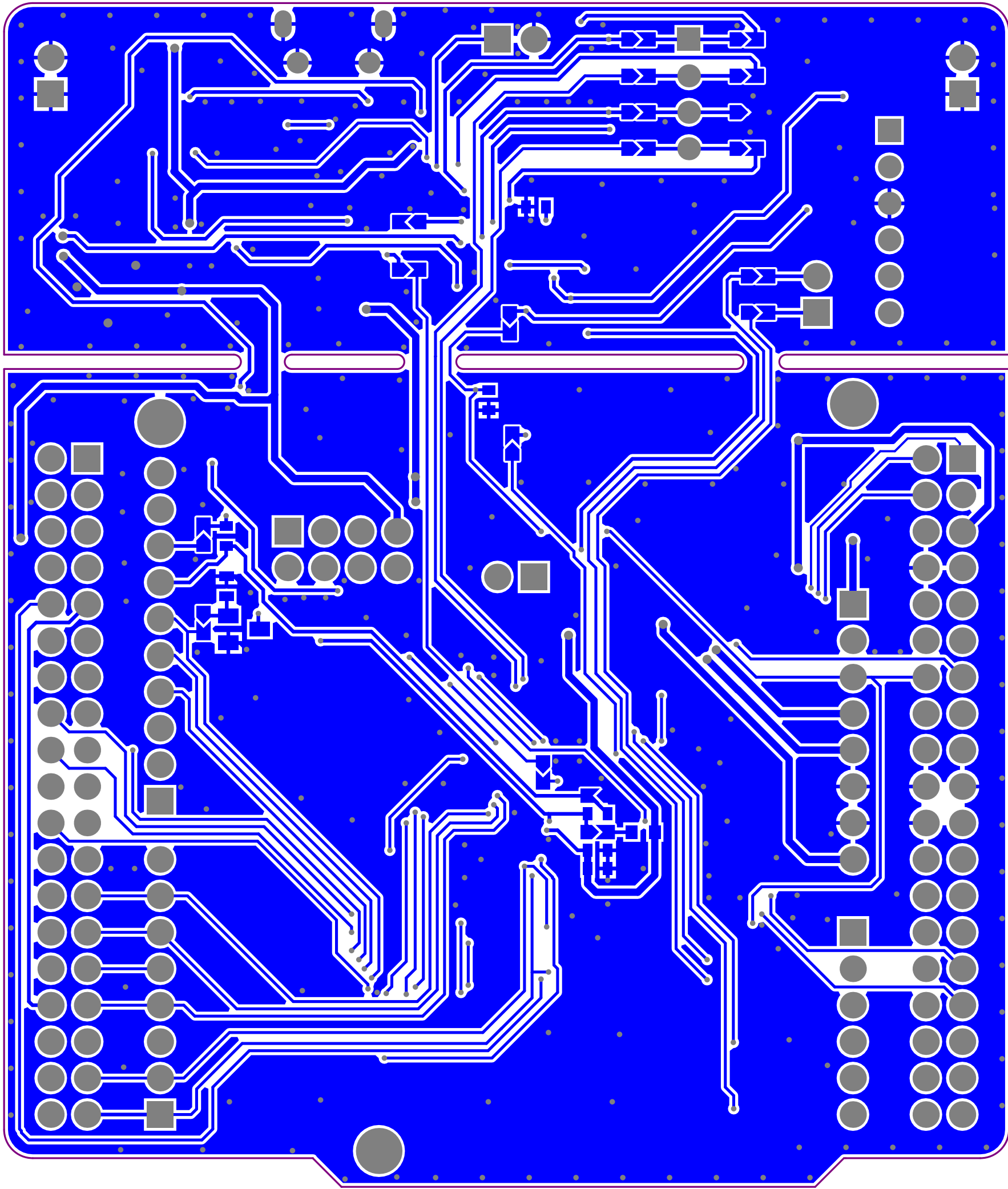
Project: NUCLEO		
Layer: <b>Top Overlay</b>	Gerber: <b>.GTO</b>	
Variant: C031C6	Ref: MB1717	
Date: 05-JAN-2021	Rev: B	




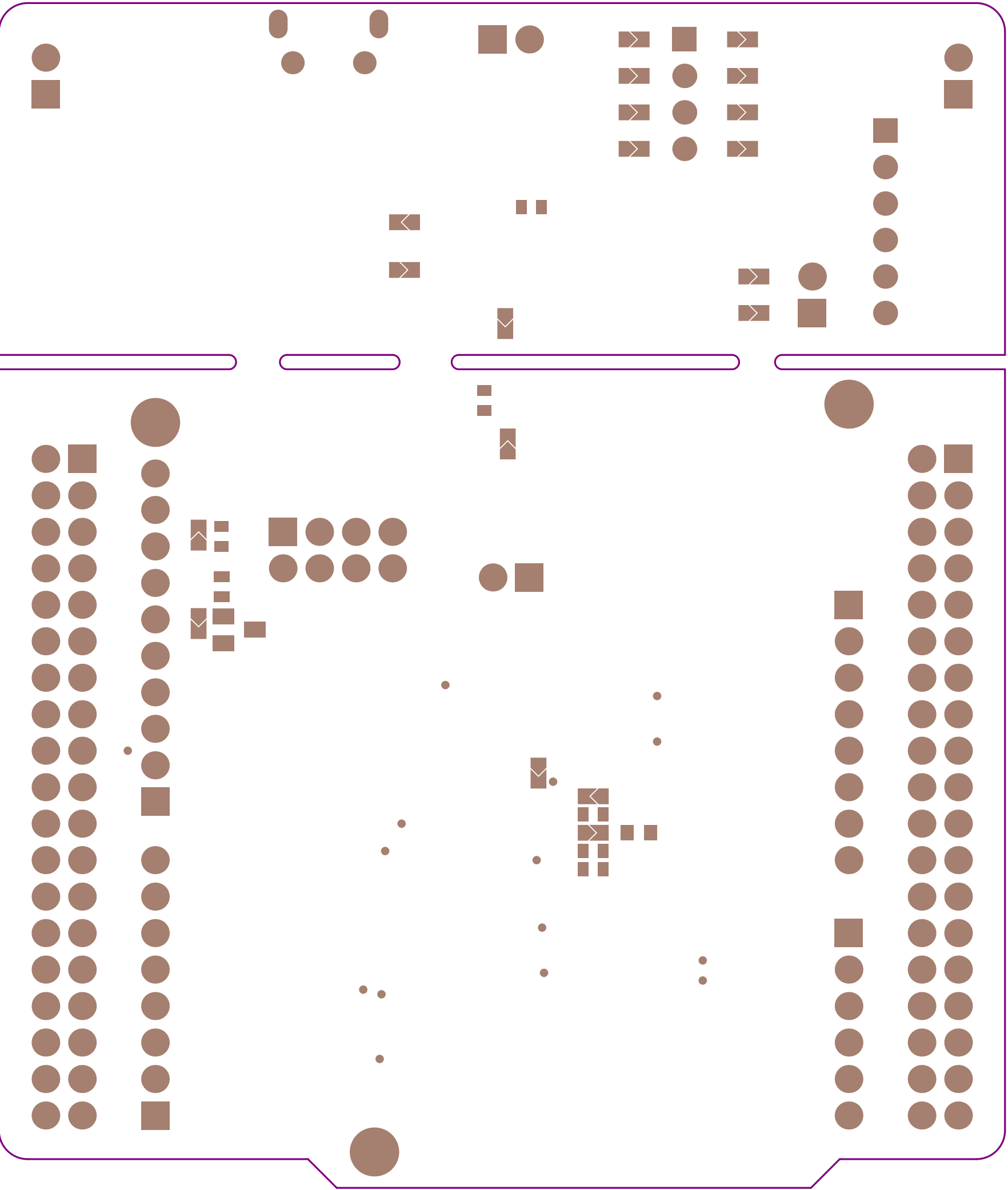
Project: NUCLEO		
Layer: <b>Top Solder</b>	Gerber: <b>.GTS</b>	
Variant: C031C6	Ref: MB1717	
Date: 05-JAN-2021	Rev: B	




Project: NUCLEO		
Layer: <b>Top Layer</b>	Gerber: <b>.GTL</b>	
Variant: C031C6	Ref: MB1717	
Date: 05-JAN-2021	Rev: B	



Project: NUCLEO		
Layer: Bottom Layer	Gerber:.GBL	
Variant: C031C6	Ref: MB1717	
Date: 05-JAN-2021	Rev: B	



Project: NUCLEO		
Layer: Bottom Solder	Gerber:.GBS	
Variant: C031C6	Ref: MB1717	
Date: 05-JAN-2021	Rev: B	



Project: NUCLEO	
Layer: Bottom Overlay	Gerber:.GBO
Variant: C031C6	Ref: MB1717
Date: 05-JAN-2021	Rev: B





PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

N/A

☐ GREEN

☒ WHITE

☐ BLUE

☐ BLACK

☐ WHITE

☐ YELLOW

☐ BLACK

☒ Blue ink PANTONE 2955

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☒ NO

☐ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

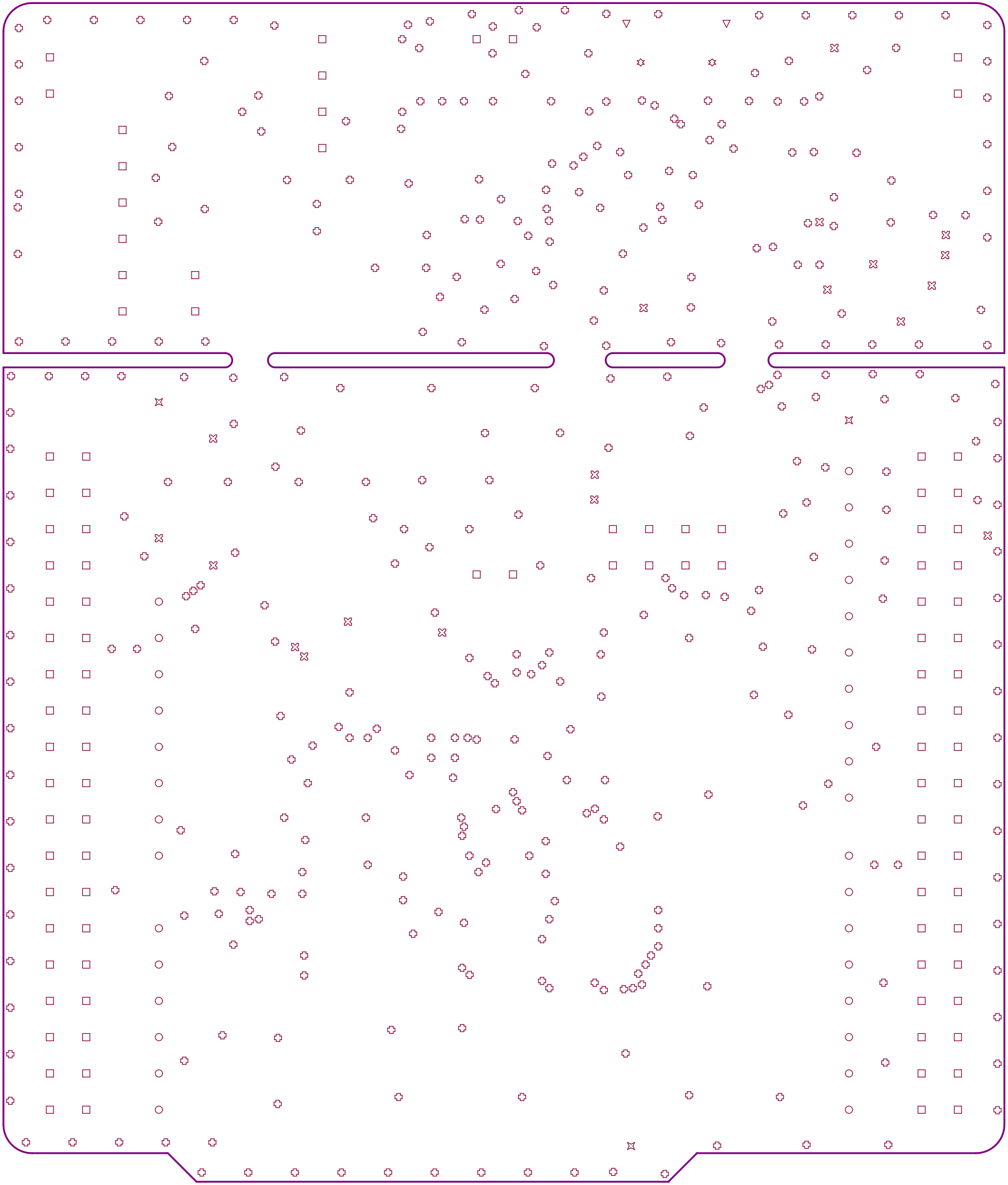
SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

PCB : TYPE 3

ASPECT-RATIO, AXE Z :  
6:1 to 8:1  
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT  
TRACKS : 0.127mm  
GAPS : 0.127mm



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
⊕	398	0.203mm (8.00mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	<Mixed>
⊗	19	0.305mm (12.00mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v64h30m0mx0
▽	2	0.600mm (23.62mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r190_120h60_130r100m195_125
☆	2	0.900mm (35.43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c150h90m155
□	104	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	<Mixed>	<Mixed>
○	32	1.100mm (43.31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	<Mixed>
✕	3	3.200mm (125.98mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c320hn320
	560 Total							

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.015mm	3.5	
1	Top Layer	Copper	0.035mm		
	Dielectric 1	FR-4	1.473mm	4.2	
2	Bottom Layer	Copper	0.035mm		
	Bottom Solder	Solder Resist	0.015mm	3.5	
	Bottom Overlay				